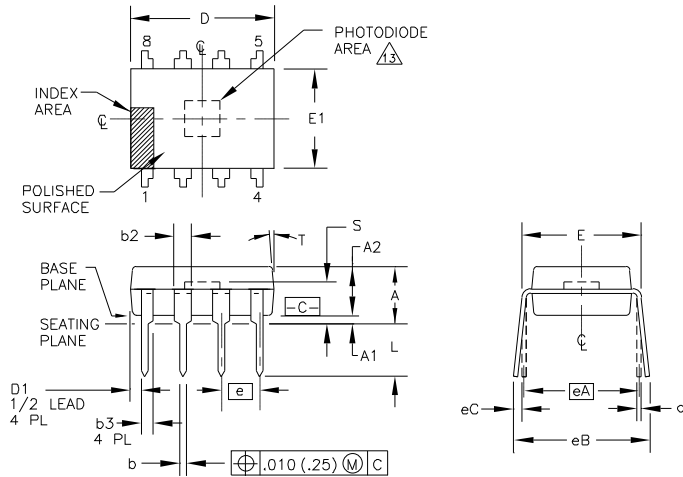


Package Number 006-1 - 8-Pin Transparent Plastic Single-Wide DIP



DIM	INCHES		MILLIMETERS		N O E
	MIN.	MAX.	MIN.	MAX.	
A	--	.165	--	4.19	3
A1	.015	--	0.38	--	3
A2	.120	.135	3.05	3.43	
b	.014	.022	0.36	0.56	
b2	.040	.050	1.02	1.27	9
b3	.030	.045	0.762	1.143	9
c	.008	.015	0.20	0.38	
D	.360	.390	9.14	9.91	4
D1	.005	--	0.13	--	4
E	.300	.325	7.62	8.26	5
E1	.238	.275	6.05	6.99	4
e	.100 BASIC		2.54 BASIC		
eA	.300 BASIC		7.63 BASIC		5
eB	--	.430	--	10.92	6

NOTES:

- ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
- D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM  $\perp$ -C-.
- eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- N IS THE MAXIMUM OF TERMINAL POSITIONS.
- POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.

- b2 AND b3 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN CROSS-HATCHED AREA.
- FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.
- CENTER OF PHOTODIODE MUST BE WITHIN .010 (0.25mm) OF CENTER OF PHOTODIODE AREA.

PACKAGE NUMBER: ZZ006-1    REV.: D  
JEDEC NUMBER: NONE



PACKAGE DRAWING

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